

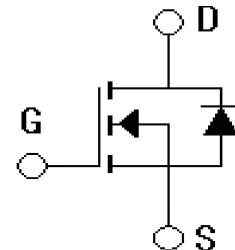
Features

- Low gate charge
- Low Crss
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability
- RoHS Compliant



Applications

- High efficiency switch mode Power supplies
- Electronic lamp ballasts based on half bridge
- UPS



Absolute Ratings (Tc=25°C)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DSS}	200	V
Drain Current -continuous	I _D T=25°C	130	A
	T=100°C	65	A
Drain Current - pulse (note 1)	I _{DM}	260	A
Gate-Source Voltage	V _{GSS}	±30	V
Single Pulsed Avalanche Energy (note 2)	E _{AS}	720	mJ
Avalanche Current (note 1)	I _{AR}	100	A
Repetitive Avalanche Current (note 1)	E _{AR}	35.7	mJ
Peak Diode Recovery dv/dt (note 3)	dv/dt	5.4	V/ns
Power Dissipation	PD TC=25°C	357	W
	-Derate above 25°C	2.86	W/°C
Operating and Storage Temperature Range	T _j , T _{STG}	-55~+150	°C
Maximum Lead Temperature for Soldering Purposes	T _L	300	°C

*Drain current limited by maximum junction temperature

Electrical Characteristics($T_{CASE}=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Tests conditions	Min	Type	Max	Units
Off-Characteristics						
Drain-Source Voltage	BV_{DSS}	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	200	-	-	V
Breakdown Voltage Temperature Coefficient	$\Delta \text{BV}_{\text{DSS}} / \Delta T_J$	$I_D=250\mu\text{A}$, referenced to 25°C	-	0.16	-	V/ $^{\circ}\text{C}$
Drain cut-off current	I_{DSS}	$V_{DS}=200\text{V}, V_{GS}=0\text{V}$ $T_j=25^{\circ}\text{C}$	-	-	1	μA
		$V_{DS}=200\text{V}, T_j=125^{\circ}\text{C}$	-	-	10	
Gate-body leakage current,forward	I_{GSSF}	$V_{DS}=0\text{V}, V_{GS}=30\text{V}$	-	-	100	nA
Gate-body leakage current,reverse	I_{GSSR}	$V_{DS}=0\text{V}, V_{GS}=-30\text{V}$	-	-	-100	nA
On-Characteristics						
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	2.0	-	4.0	V
Static Drain-Source On-Resistance	$R_{DS(\text{ON})}$	$V_{GS}=10\text{V}, I_D=50\text{A}$ (note 3)	-	8.3	12	$\text{m}\Omega$
Forward Transconductance	g_{fs}	$V_{DS}=40\text{V}, I_D=130\text{A}$ (note 3)	-	66	-	S
Dynamic Characteristics						
Input capacitance	C_{iss}	$V_{DS}=100\text{V},$ $V_{GS}=0\text{V},$ $f=1.0\text{MHz}$	-	4100	-	pF
Output capacitance	C_{oss}		-	420	-	pF
Reverse transfer capacitance	C_{rss}		-	10	-	pF

Switching Characteristics						
Turn-On delay time	$t_{d(on)}$	$V_{DD}=160\text{V}, I_D=130\text{A},$ $R_G=25\Omega,$ $V_{GS}=10\text{V}$ (note 4,5)	-	56	112	ns
Turn-On rise time	t_r		-	408	500	ns
Turn-Off delay time	$T_{d(off)}$		-	270	550	ns
Turn-Off Fall time	t_f		-	240	490	ns
Total Gate Charge	Q_g	$V_{DS}=160\text{V},$ $I_D=130\text{A},$ $V_{GS}=10\text{V}$ (note4,5)	-	60	-	nC
Gate-Source charge	Q_{gs}		-	16	-	nC
Gate-Drain charge	Q_{gd}		-	20	-	nC
Drain-Source Diode Characteristics and Maximum Ratings						

Drain-Source Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_S=10A$ (note 3)	-	0.73	1.2	V
Maximum Continuous Drain-Source Diode Forward Current		I_S	-	-	130	A
Maximum Pulsed Drain-Source Diode Forward Current		I_{SM}	-	-	260	A
Reverse recovery time	t_{rr}	$V_{GS}=0V, I_F=130A$	-	175	-	ns
Reverse recovery charge	Q_{rr}	$dI_F/dt=100A/\mu s$ (note 3)	-	1.23	-	uC

Thermal Characteristic

Parameter	Symbol	Value		Unit
		TO-247	TO-220	
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.35		°C/W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	60		°C/W

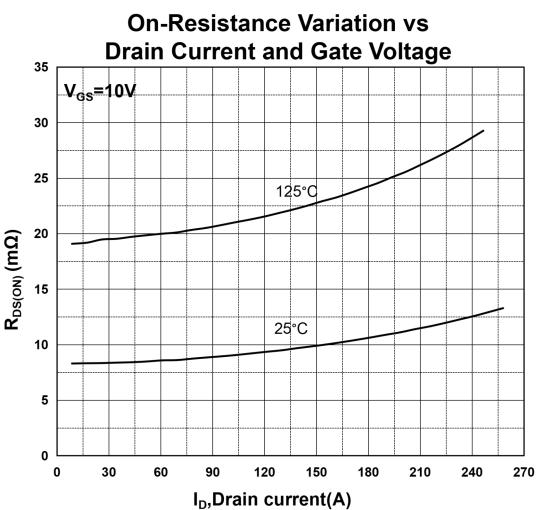
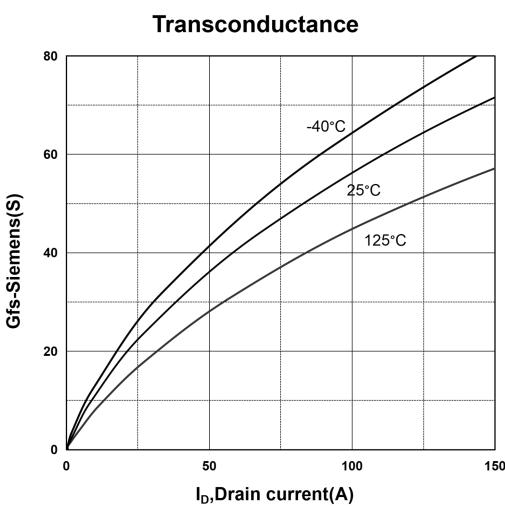
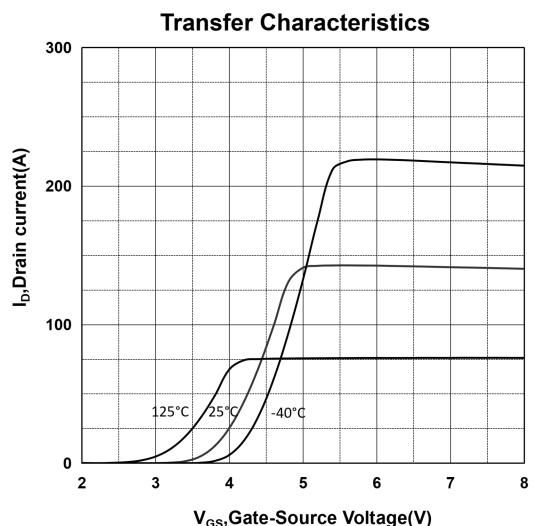
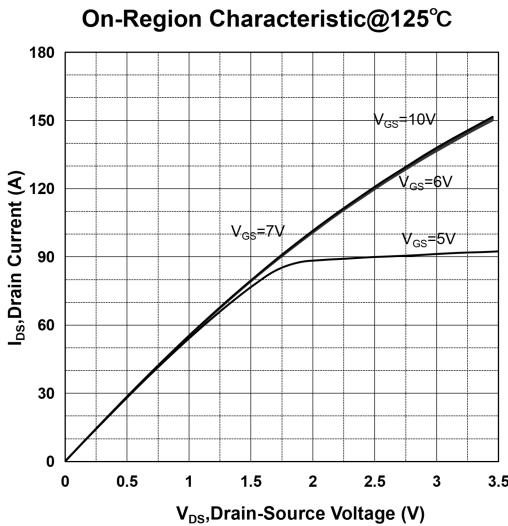
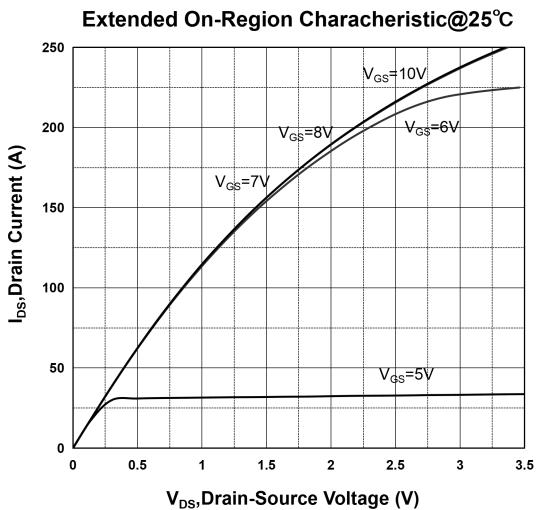
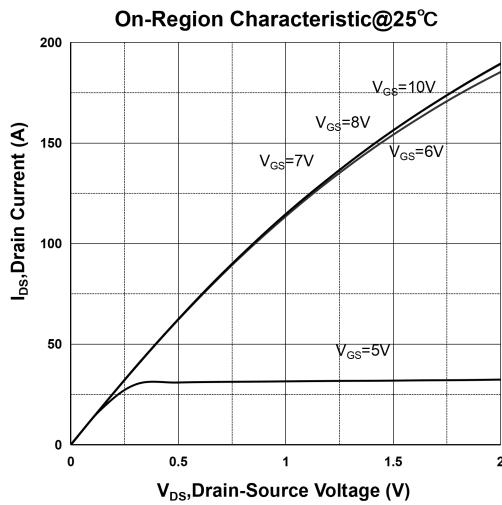
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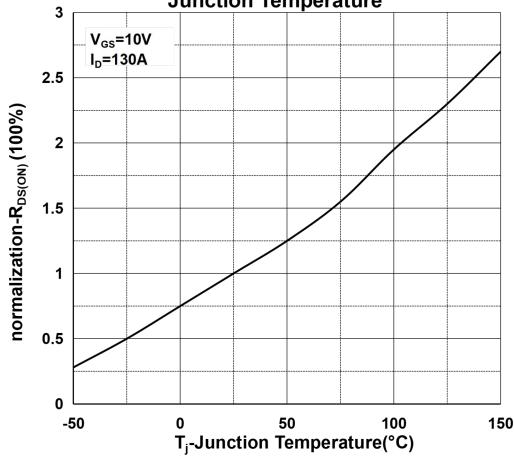
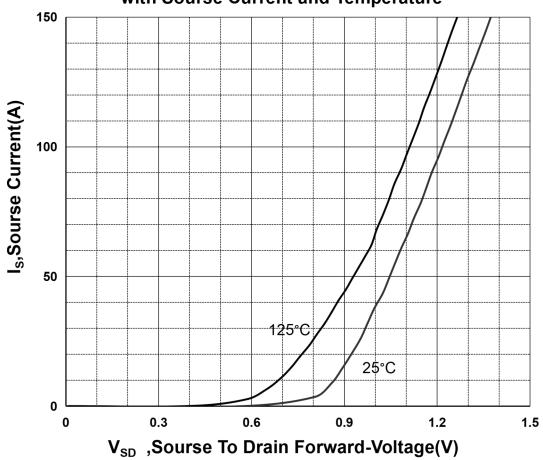
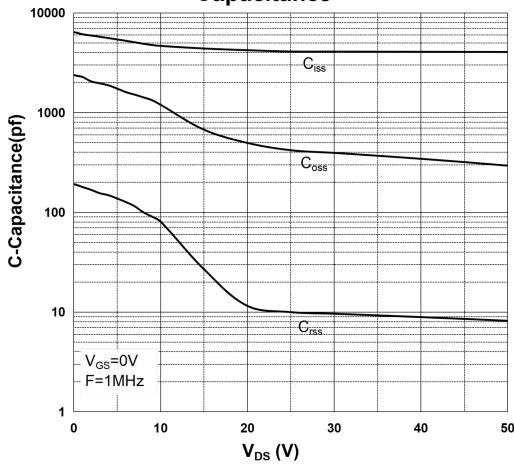
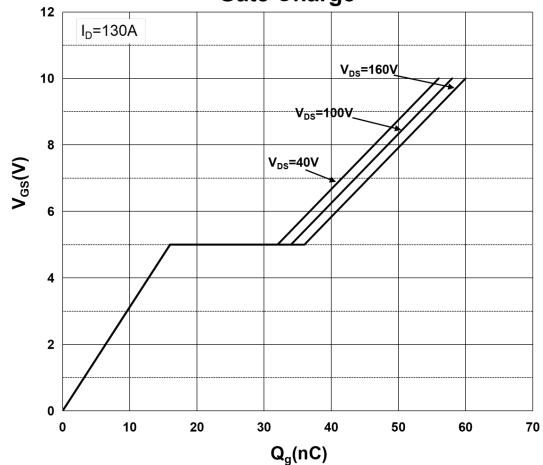
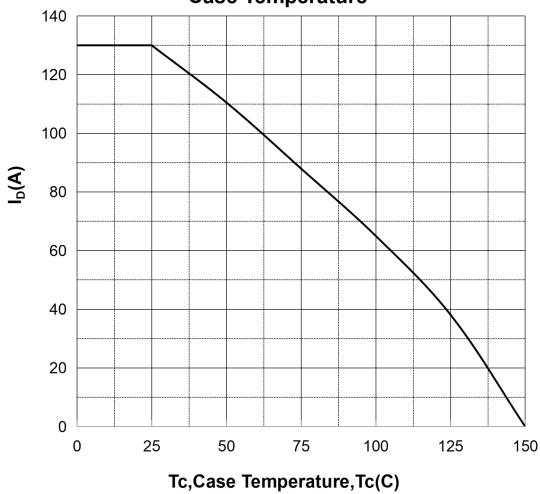
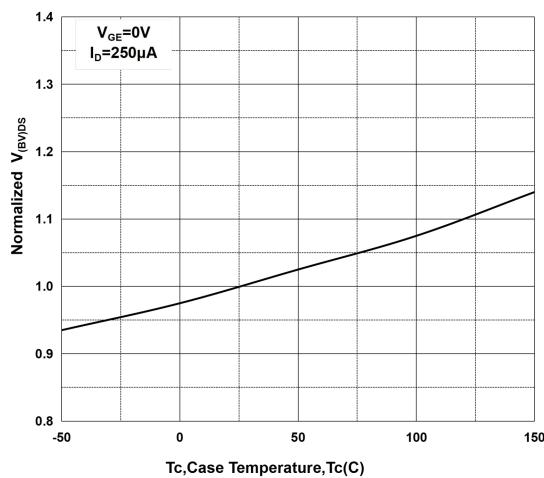
- 1: Pulse width limited by maximum junction temperature
- 2: L=0.5mH, $I_{AS}=100A$, $V_{DD}=50V$, $RG=25 \Omega$, Starting $TJ=25^\circ C$
- 3: $I_{SD} \leq 100A, di/dt \leq 300A/\mu s, V_{DD} \leq BV_{DSS}$, Starting $TJ=25^\circ C$
- 4: Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$
- 5: Essentially independent of operating temperature

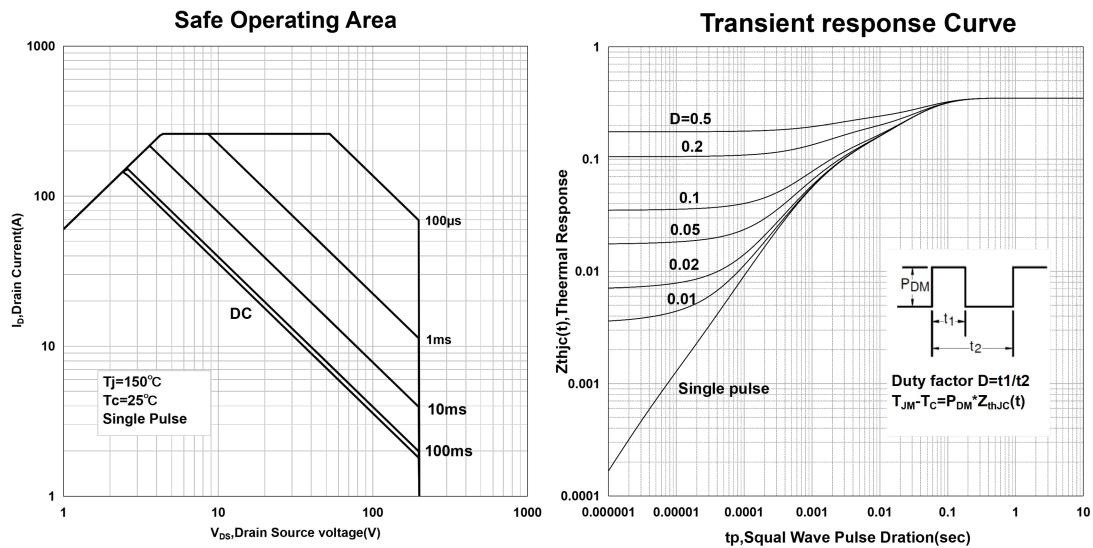
Ordering message

Marking	Package
MS130N20JDC0	TO-247
MS130N20JDT0	TO-220

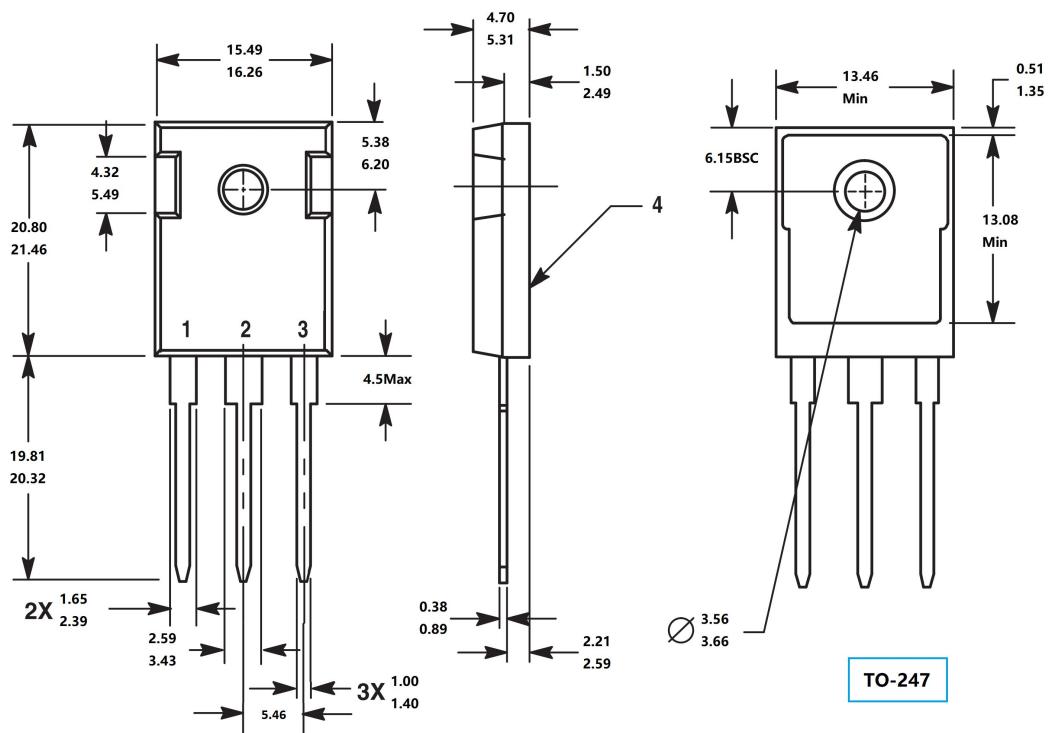
Electrical Characteristics

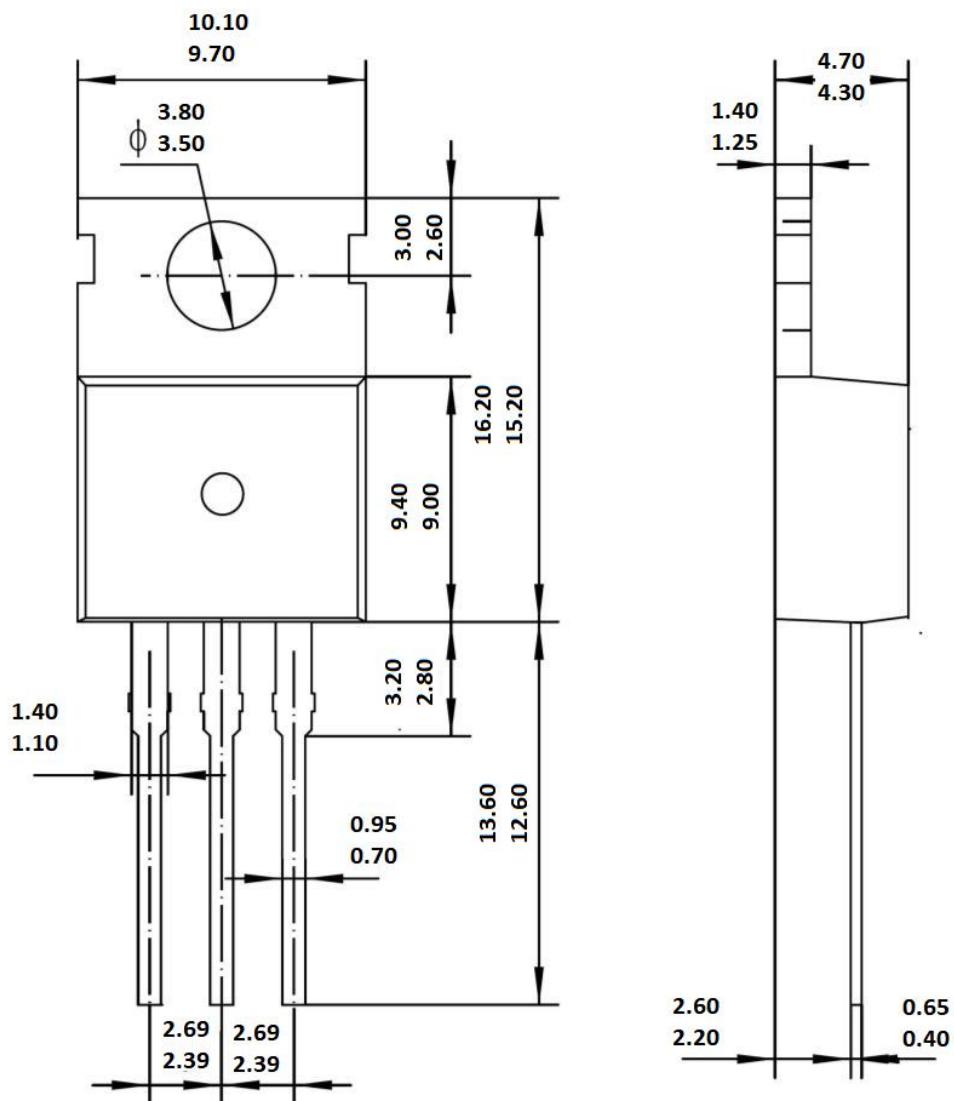


Normalization On-Resistance Variation vs Junction Temperature

Body Diode Forward Voltage Variation with Source Current and Temperature

Capacitance

Gate Charge

Maximum Drain Current vs Case Temperature

Normalized V_{(BV)DS} vs temperature




Package Mechanical DATA





TO-220

Unit: mm